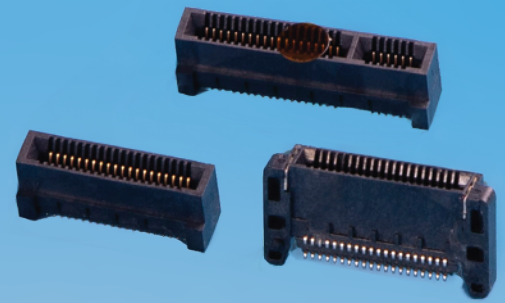




8206

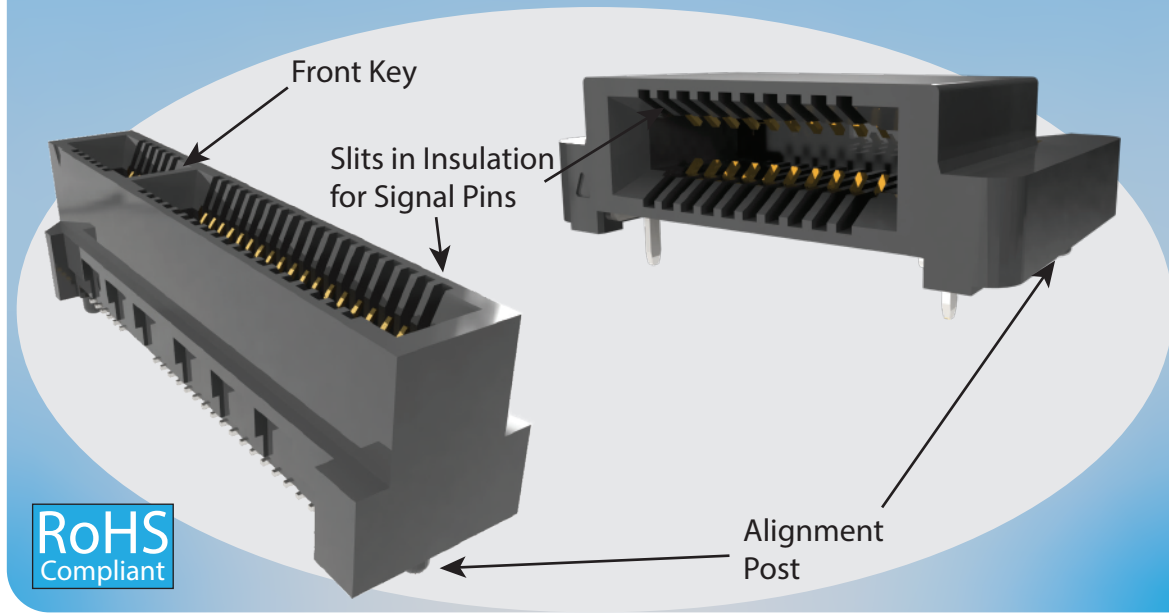
0.80 mm (0.0315")



High Speed Card Edge Connector

Specification

Insulator Material:
Housing: Black LCP, Glass Filled, UL94V-0
Contact:
High Performance Copper Alloy
Plating:
*Au over 50 μ" (1.27μm) Ni
Current Rating:
3.1A
Operating Temperature:
-55°C ~ + 125°C
* Refer to Product Drawing for Specific Details



Positions

Right Angle SMD:
20, 40
Right Angle SMD with Key:
100
Vertical SMD:
20, 40
Vertical SMD with Key:
26, 50, 80, 100, 120
*Position is Total Pin Count.
Ex: 2 row X 10 pin/row = 20 Position

8206-2 Mating Details	
Card Edge Thickness	—1.575 or 1.6 mm (.062 or .063")
Insertion Depth	—3.15 to 5.55 mm (.124 to .219")

High Speed Performance

28 Gbps Differences in SI Testing Boards Result in Differences in Measured Speed.

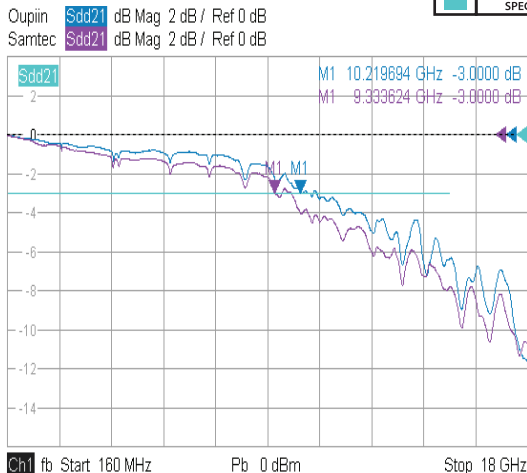
Options

Contact Plating:
Gold Flash
10μ" Gold
30μ" Gold
Orientation Type:
Right Angle SMD
Right Angle SMD with Key
Vertical SMD
Vertical SMD with Key
Packaging:
Tape & Reel
Tube
Other:
Pick & Place Mylar Pad Post

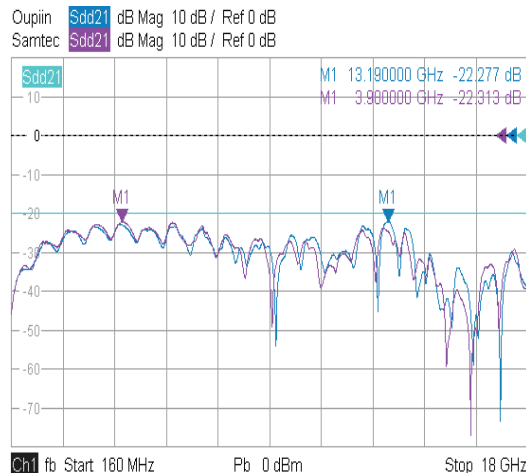
SI Report

For Vertical SMD

Differential Pair Insertion Loss GSSG



Differential Pair Near End Crosstalk GAAGQQG



Product Specification, Drawings, Certifications, Test Reports and SI Report Available Upon Request

